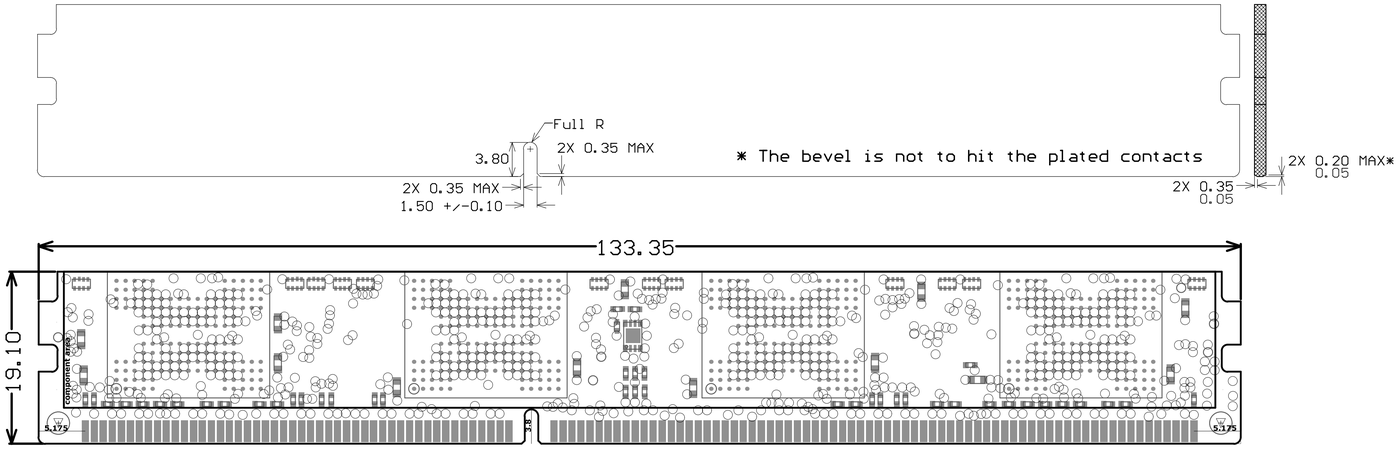
Mechanical Layer	Usage
1	Components body outline, top (with ref.des.)
2	Board outline
3	Additional dimensions
4	Board dimensions
6	Layer Stack table
12	Fabrication drawing
14	Components body outline, bottom (with ref.des.)

Drill Table

○	720	0.2mm (7.874mil)	PTH	Round
▽	2	2.5mm (98.425mil)	NPTH	Round
	722 Total			

Layer Stack Table

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.50mil	3.5	
3	Top Layer	Copper	2.13mil		
4	Dielectric 1	FR-4	2.95mil	4.2	
5	GND1	Copper	0.59mil		
6	Dielectric 2	FR-4	2.95mil	4.2	
7	Signal Layer 1	Copper	0.59mil		
8	Dielectric 3	FR-4	5.98mil	4.2	
9	POW	Copper	0.59mil		
10	Dielectric 4	FR-4	2.95mil	4.2	
11	Signal Layer 2	Copper	0.59mil		
12	Dielectric 5	FR-4	10.00mil	4.2	
13	Signal Layer 3	Copper	0.59mil		
14	Dielectric 6	FR-4	2.95mil	4.2	
15	GND2	Copper	0.59mil		
16	Dielectric 7	FR-4	5.98mil	4.2	
17	Signal Layer 4	Copper	0.59mil		
18	Dielectric 8	FR-4	2.95mil	4.2	
19	GND3	Copper	0.59mil		
20	Dielectric 9	FR-4	2.95mil	4.2	
21	Bottom Layer	Copper	2.13mil		
22	Bottom Solder	Solder Resist	0.50mil	3.5	
23	Bottom Overlay				



Board Details

Number of layers:	**10**
Dimensions:	**133.35x19.1mm**
Material type:	**FR4Tg130**
Finish plating:	**ENIG (for the board)** **1-2um Hard Gold over 3-6um Nickel (for EDGE connector fingers)**
Outer copper Wt:	**1.5 oz (final)**
Inner coper Wt:	**0.5 oz**
Gold finger:	**Yes**
Thickness:	**1.26mm +/-10%**
Min. trace/space:	**0.102/0.102mm**
Min. via:	**0.4/0.2mm**
Min. hole:	**0.2mm**
Array:	**Yes**
Array dim:	**TBD**
No. of boards/array:	**TBD**
X-out not allowed:	**NA**
X-out Qty:	**NA**
Solder mask:	**Top/Bottom Green. All vias are tented.**
Silk screen:	**White non-conductive ink. No ink over component pads.**
RoHS:	**Yes**
Peelable mask:	**No**
Plated slots:	**No**
Controlled dielectric:	**NA**
Controlled impedance:	**Yes**

Single ended traces:

Layer	Trace width	Ref. Layer	Target Impedance (+/- 10%)
Top	0.102mm	GND1	51.6 Ohm
Sig L1	0.102mm	GND1	43.9 Ohm
Sig L2	0.102mm	POW	47.3 Ohm
Sig L3	0.102mm	GND2	47.3 Ohm
Sig L4	0.102mm	GND2	43.9 Ohm
Bottom	0.102mm	GND3	51.6 Ohm

Differential Pairs: **No**

Board Name	**NVM UDIMM Module**
Project Rev.	**1.0**
Board Number	**TBD**
Fabrication Rev.	**B**
Date	**8/4/2015**